

Photocouplers InGaAs Infrared LED & Photo Transistor

TLP388

1. Applications

- · Programmable Logic Controllers (PLCs)
- · Air Conditioner Inverters

2. General

TLP388 consists of phototransistors optically coupled to InGaAs infrared emitting diodes. The TLP388 is housed in the thin SO6L (4pin) package and that guarantees high temperature operation (T_a = 125 °C max).

With the high brakedown voltage between the collector and emitter (V_{CEO}) 350V, TLP388 is suitable for use in programmable logic controllers (PLCs), and home appliances, include air conditioners.

3. Features

- (1) Collector-emitter voltage: 350 V (min)
- (2) Current transfer ratio: 50 % (min) (@ $I_F = 5$ mA, $V_{CE} = 5$ V) Rank GB: 100 % (min) (@ $I_F = 5$ mA, $V_{CE} = 5$ V)
- (3) Isolation voltage: 5000 Vrms (min)
- (4) Operating temperature range: -55 to 125 °C
- (5) Safety standards

UL-approved: UL1577, File No.E67349

cUL-approved: CSA Component Acceptance Service No.5A File No.E67349

VDE-approved: EN60747-5-5, EN60065 or EN60950-1 (Note 1)

EN62368-1 (Pending) (Note 1)

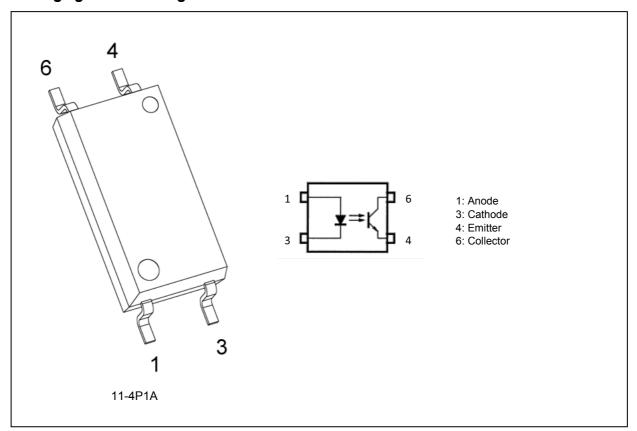
CQC-approved: GB4943.1, GB8898 Thailand Factory (Pending)



Note1: When a VDE approved type is needed, please designate the **Option (D4)**.



4. Packaging and Pin Assignment



5. Mechanical Parameters

Characteristics	Min	Unit
Creepage distances	8.0	mm
Clearance	8.0	
Internal isolation thickness	0.4	



6. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

	Characteristics		Symbol	Note	Rating	Unit
LED	Input forward current		I _F		50	mA
	Input forward current derating	$(T_a \ge 90 ^{\circ}C)$	$\Delta I_F/\Delta T_a$		-1.11	mA/°C
	Input forward current (pulsed)		I _{FP}	(Note 1)	1	Α
	Input power dissipation		P_{D}		100	mW
	Input power dissipation derating	$(T_a \ge 90 ^{\circ}C)$	$\Delta P_D/\Delta T_a$		-2.22	mW/°C
	Input reverse voltage		V_R		5	V
	Junction temperature		Tj		135	°C
Detector	Collector-emitter voltage		V _{CEO}		350	V
	Emitter-collector voltage		V _{ECO}		7	
	Collector current		Ic		50	mA
	Collector power dissipation		P _C		150	mW
	Collector power dissipation derating	$(T_a \geq 25~^{\circ}\text{C})$	$\Delta P_{C}/\Delta T_{a}$		-1.36	mW/°C
	Junction temperature		Tj		135	°C
Common	Operating temperature		T _{opr}		-55 to 125	°C
	Storage temperature		T _{stg}		-55 to 125	
	Lead soldering temperature	(10 s)	T _{sol}		260	
	Total power dissipation		P _T		250	mW
	Total power dissipation derating	$(T_a \geq 25~^{\circ}\text{C})$	$\Delta P_T/\Delta T_a$		-2.27	mW/°C
	Isolation voltage	AC, 60 s, R.H. ≤ 60 %	BV _S	(Note 2)	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width (PW) \leq 0.1 ms, f = 100 Hz

Note 2: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.

7. Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

	Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
LED	Input forward voltage	V _F		I _F = 10 mA	1.1	1.25	1.4	V
	Input reverse current	I _R		V _R = 5 V	_	_	10	μΑ
	Input capacitance	Ct		V = 0 V, f = 1 MHz	_	30	_	pF
Detector	Collector-emitter breakdown voltage	V _{(BR)CEO}		I _C = 0.1 mA	350			V
	Emitter-collector breakdown voltage	V _{(BR)ECO}		I _E = 0.1 mA	7			
	Dark Current	I _{DARK}		V _{CE} = 300 V	_	0.01	0.2	μА
				V _{CE} = 300 V, T _a = 85 °C	_	_	50	
	Collector-emitter capacitance	C _{CE}		V = 0 V, f = 1 MHz	_	10	_	pF



8. Coupled Electrical Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Current transfer ratio	I _C /I _F	(Note 1)	I _F = 5 mA, V _{CE} = 5 V	50	_	600	%
			$I_F = 5 \text{ mA}, V_{CE} = 5 \text{ V}, \text{ Rank GB}$	100		600	
Saturated current transfer ratio	I _C /I _{F(sat)}		I _F = 10 mA, V _{CE} = 0.4 V	_	60		
			I_F = 10 mA, V_{CE} = 0.4 V, Rank GB	30	_	_	
Collector-emitter saturation voltage	V _{CE(sat)}		I _C = 2.4 mA, I _F = 8 mA	_	_	0.4	V
			I _C = 0.2 mA, I _F = 1 mA	_	0.2	_	
			I_C = 0.2 mA, I_F = 1 mA, Rank GB	_	_	0.4	
OFF-state collector current	I _{C(off)}		$V_F = 0.7 \text{ V}, V_{CE} = 350 \text{ V}$			200	μΑ

Note 1: See Table 8.1 for current transfer ratio.

Table 8.1 Current Transfer Ratio (CTR) Rank (Note) (Unless otherwise specified, Ta = 25 °C)

Rank	Test Condition	Current transfer ratio I _C /I _F Min	Current transfer ratio I _C /I _F Max	Marking of classification	Unit
Blank	I _F = 5 mA, V _{CE} = 5 V	50	600	Blank, GB	%
GB		100	600	GB	

Note: Specify both the part number and a rank in this format when ordering.

Example: TLP388(GB,E

For safety standard certification, however, specify the part number alone.

Example: TLP388(GB,E → TLP388

9. Isolation Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Total capacitance (input to output)	Cs	(Note 1)	V _S = 0 V, f = 1 MHz		8.0		pF
Isolation resistance	R _S	(Note 1)	V _S = 500 V, R.H. ≤ 60 %	1 × 10 ¹²	1014		Ω
Isolation voltage	BVS	(Note 1)	AC, 60 s	5000			Vrms
			AC, 1 s in oil		10000		
			DC, 60 s in oil	_	10000	_	Vdc

Note 1: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.



10. Switching Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Rise time	t _r		V _{CC} = 10 V, I _C = 2 mA,	_	2	_	μS
Fall time	t _f		$R_L = 100 \Omega$	_	3	_	
Turn-on time	t _{on}			_	3	_	
Turn-off time	t _{off}			_	3	_	
Turn-on time	t _{on}		See Fig. 10.1	_	3	_	
Storage time	t _s		$R_L = 1.9 \text{ k}\Omega, V_{CC} = 5 \text{ V},$ $I_F = 16 \text{ mA}$	_	60	_	
Turn-off time	t _{off}				80		

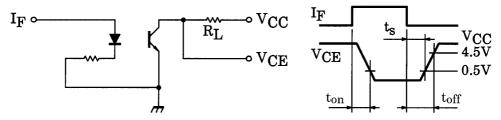


Fig. 10.1 Switching Time Test Circuit and Waveform

11. Characteristics Curves (Note)

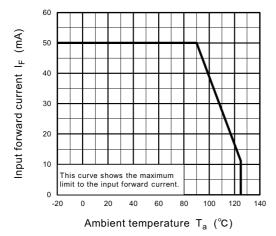


Fig. 11.1 I_F - T_a

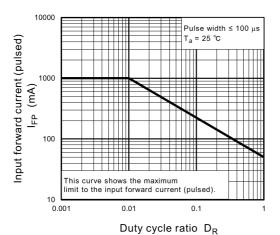


Fig. 11.3 IFP - DR

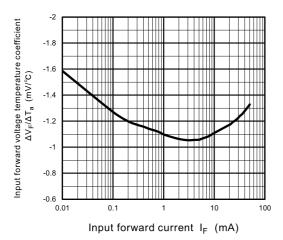


Fig. 11.5 $\Delta V_F/\Delta T_a - I_F$

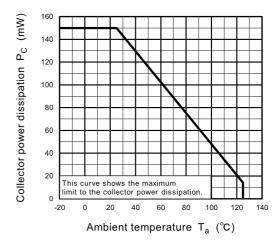


Fig. 11.2 P_C - T_a

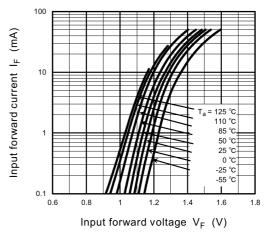


Fig. 11.4 I_F - V_F

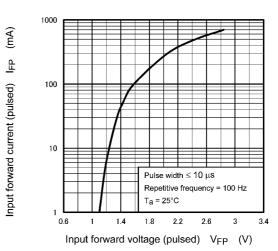


Fig. 11.6 I_{FP} - V_{FP}

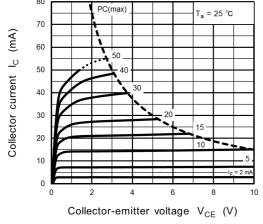


Fig. 11.7 I_C - V_{CE}

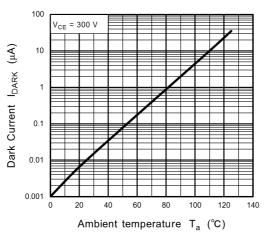


Fig. 11.9 IDARK - Ta

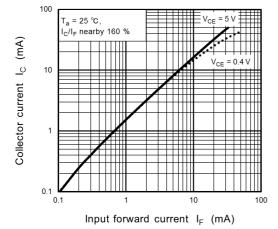


Fig. 11.11 I_C - I_F

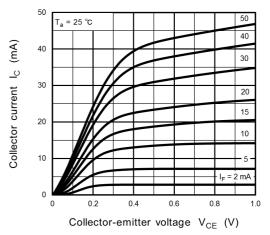


Fig. 11.8 I_C - V_{CE}

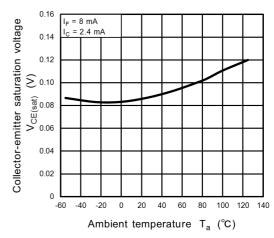


Fig. 11.10 V_{CE(sat)} - T_a

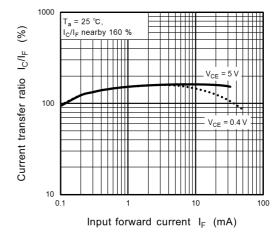
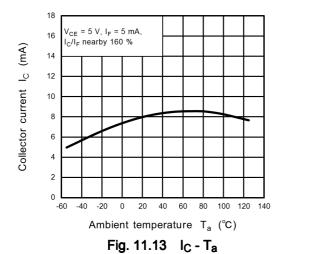
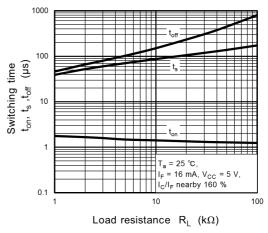


Fig. 11.12 I_C/I_F - I_F





TLP388

Fig. 11.14 Switching Time - RL

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



12. Soldering and Storage

12.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

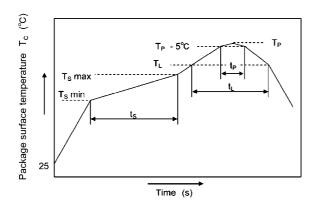
When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



	Symbol	Min	Max	Unit
Preheat temperature	Ts	150	200	°C
Preheat time	ts	60	120	S
Ramp-up rate (T _L to T _P)			3	°C/s
Liquidus temperature	TL	217		°C
Time above T _L	t _L	60	150	S
Peak temperature	T _P		260	°C
Time during which T_c is between $(T_P - 5)$ and T_P	t _P		30	s
Ramp-down rate (T _P to T _L)			6	°C/s

Fig. 12.1.1 An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

· When using soldering flow

Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds. Mounting condition of 260 °C within 10 seconds is recommended.

Flow soldering must be performed once.

· When using soldering Iron

Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C

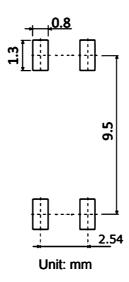
Heating by soldering iron must be done only once per lead.

12.2. Precautions for General Storage

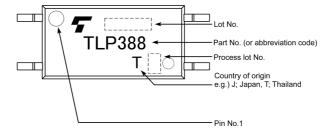
- · Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- · When restoring devices after removal from their packing, use anti-static containers.
- · Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.



13. Land Pattern Dimensions (for reference only)



14. Marking





15. EN60747-5-5 Option (D4) Specification

Part number: TLP388 (Note 1)

• The following part naming conventions are used for the devices that have been qualified according to option (D4) of EN60747.

Example: TLP388(D4GB-TL,E(T

D4: EN60747 option TL: Tape type(TPL)

E: [[G]]/RoHS COMPATIBLE (Note 2)

T: Domestic ID (Country/Region of origin: Thailand)

Note 1: Use TOSHIBA standard type number for safety standard application.

e.g., TLP388(D4GB-TL,E(T \rightarrow TLP388

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

Description	Symbol	Rating	Unit
Application classification			_
for rated mains voltage ≤ 150 Vrms for rated mains voltage ≤ 300 Vrms		I-IV I-III	
Climatic classification		55 / 125 / 21	_
Pollution degree		2	_
Maximum operating insulation voltage	VIORM	1230	Vpeak
Input to output test voltage, Method A $V_{pr} = 1.6 \times V_{IORM}, \text{ type and sample test} \\ t_p = 10 \text{ s, partial discharge} < 5 \text{ pC}$	V _{pr}	1970	Vpeak
Input to output test voltage, Method B $V_{pr} = 1.875 \times V_{IORM}, \ 100 \ \% \ production \ test$ $t_p = 1 \ s, \ partial \ discharge < 5 \ pC$	V _{pr}	2310	Vpeak
Highest permissible overvoltage (transient overvoltage, t _{pr} = 60 s)	V _{TR}	8000	Vpeak
Safety limiting values (max. permissible ratings in case of fault, also refer to thermal derating curve) current (input current I _F , P _{so} = 0)	l _{si}	250	mA
power (output or total power dissipation) temperature	P _{so} T _s	400 150	mW °C
Insulation resistance V_{IO} = 500 V, T_a = 25 °C V_{IO} = 500 V, T_a = 100 °C V_{IO} = 500 V, T_a = T_s	R _{si}	$\geq 10^{12}$ $\geq 10^{11}$ $\geq 10^{9}$	Ω

Fig. 15.1 EN60747 Insulation Characteristics



Table 15.1 Insulation Related Specifications (Note)

Isoration related specification	Symbol	TLP388
Minimum creepage distance	Cr	8.0 mm
Minimum clearance	CI	8.0 mm
Minimum insulation thickness	ti	0.4 mm
Comparative tracking index	CTI	175

Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.



Fig. 15.2 Marking on packing for EN60747

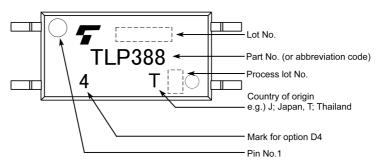
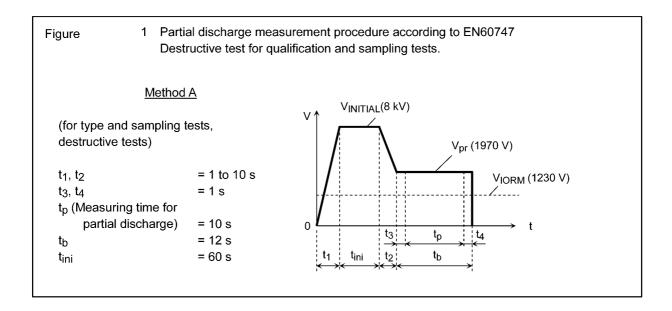
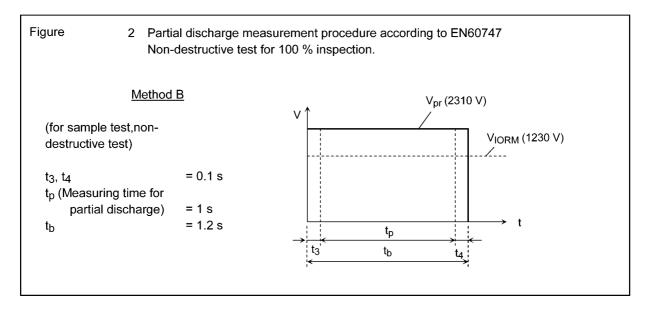


Fig. 15.3 Marking Example (Note)

Note: The above marking is applied to the photocouplers that have been qualified according to option (D4) of EN60747.

TOSHIBA





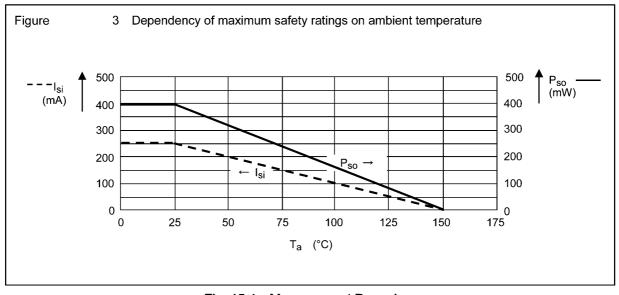


Fig. 15.4 Measurement Procedure



16. Embossed-Tape Packing (TPL),(TPR) Specification for Mini-Flat Photocouplers

16.1. Applicable Package

Package Name	Product Type
SO6L	Long creepage mini flat coupler

16.2. Product Naming Conventions

Type of package used for shipment is denoted by a symbol suffix after a part number. The method of classification is as below.

Example) TLP388(GB-TPL,E(T

Part number: TLP388

CTR rank: GB Tape type: TPL

[[G]]/RoHS COMPATIBLE: E (Note 1)

Domestic ID (Country/Region of origin: Thailand): T

Note 1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

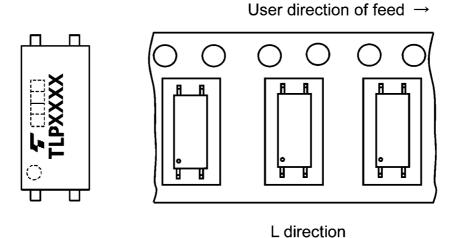


16.3. Tape Dimensions Specification

Tape Type	Division	Packing Amount (A unit per reel)
TPL	L direction	3000
TPR	R direction	3000

16.3.1. Orientation of Device in Relation to Direction of Feed

Device orientation in the carrier cavities as shown in the following figure.



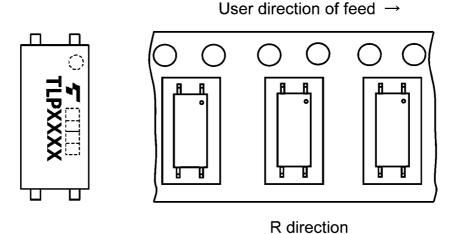


Fig. 16.3.1.1 Device Orientation

16.3.2. Empty Cavities

Characteristics	Criterion	Remarks
Occurrences of 2 or more successive empty cavities	0 device	Within any given 40-mm section of tape, not including leader and trailer
Single empty cavity	6 devices (max) per reel	Not including leader and trailer

16.3.3. Tape Leader and Trailer

The start end of the tape has 25 or more empty cavities. The hub end of the tape has 20 or more empty cavities and 1 empty turns for a cover tape.



16.3.4. Tape Dimensions

Tape material: Plastic (for protection against static electricity)

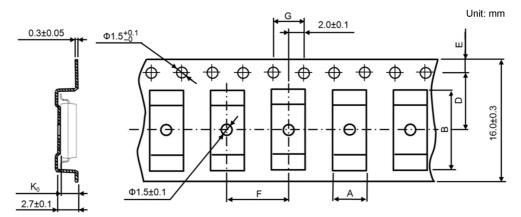


Fig. 16.3.4.1 Tape dimension

Table 16.3.4.1 Tape Dimensions (unit: mm, tolerance: ±0.1)

Symbol	Dimension	Remark
Α	4.24	_
В	10.4	_
D	7.5	Center line of embossed cavity and sprocket hole
E	1.75	Distance between tape edge and sprocket hole center
F	8.0	_
G	4.0	Cumulative error +0.2/-0.3 (max) per 10 sprocket holes
K ₀	2.4	Internal space



16.3.5. Reel Specification

Material: Plastic

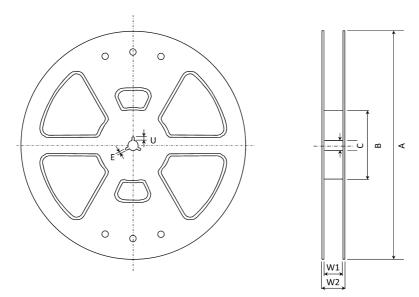


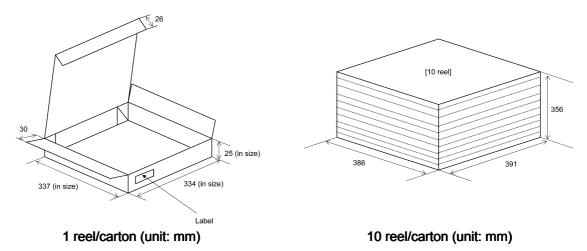
Fig. 16.3.5.1 Reel Dimensions

Table 16.3.5.1 Reel Dimensions (unit: mm)

Symbol	Dimension
Α	φ330 ± 2
В	φ100 ± 1
С	φ13 ± 0.5
E	2.0 ± 0.5
U	4.0 ± 0.5
W1	17.5 ± 0.5
W2	21.4 ± 1.0

16.4. Packing (Note)

Either one reel or ten reels of photocouplers are packed in a shipping carton.



Note: Taping reel diameter: $\phi 330 \pm 2 \text{ mm}$

16.5. Label Format

- (1) Carton: The label provides the part number, quantity, lot number, the Toshiba logo, etc.
- (2) Reel: The label provides the part number, the taping name, quantity, lot number, etc.



16.6. Ordering Information

When placing an order, please specify the part number, CTR rank, tape type and quantity as shown in the following example.

Example) TLP388(GB-TPL,E(T 3000 pcs

Part number: TLP388

CTR rank: GB

Tape type: TPL (L direction)

[[G]]/RoHS COMPATIBLE: E (Note 1)

Domestic ID (Country/Region of origin: Thailand): T Quantity (must be a multiple of 3000): 3000 pcs

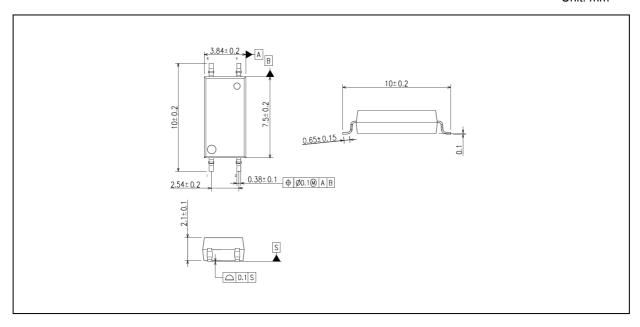
Note 1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.



Package Dimensions

Unit: mm



Weight: 0.128 g (typ.)

	Package Name(s)
TOSHIBA: 11-4P1A	



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